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| <input type="checkbox"/> | <p><b>1. Single wafer cleaning and drying: particle removal via a non-contact, non-damaging megasc by a high performance "Rotagoni" dry</b><br/> Lauerhaas, J.; Mertens, P.W.; Fyen, W.; Kenis, K.; Meuris, M.; Nicolosi, T.; Bran, M.; Fraser, B.; Fr Heyns, M.;<br/> Semiconductor Manufacturing, 2000. Proceedings of ISSM 2000. The Ninth International Symposi<br/> 26-28 Sept. 2000 Page(s):157 - 160<br/> Digital Object Identifier 10.1109/ISSM.2000.993638<br/> <a href="#">AbstractPlus</a>   Full Text: <a href="#">PDF</a>(541 KB) IEEE CNF</p> |
| <input type="checkbox"/> | <p><b>2. Novel electrolysis-ionized-water cleaning technique for the chemical-mechanical polishing (</b><br/> Aoki, H.; Nakajima, T.; Kikuta, K.; Hayashi, Y.;<br/> VLSI Technology, 1994. Digest of Technical Papers. 1994 Symposium on<br/> 7-9 June 1994 Page(s):79 - 80<br/> Digital Object Identifier 10.1109/VLSIT.1994.324368<br/> <a href="#">AbstractPlus</a>   Full Text: <a href="#">PDF</a>(152 KB) IEEE CNF</p>  |
| <input type="checkbox"/> | <p><b>3. Yield enhancement through understanding the particle adhesion and removal mechanisms i</b><br/> <b>CMP cleaning processes</b><br/> Taylor, J.; Busnaina, A.;<br/> Advanced Semiconductor Manufacturing Conference and Workshop, 2000 IEEE/SEMI<br/> 12-14 Sept. 2000 Page(s):14 - 17<br/> Digital Object Identifier 10.1109/ASMC.2000.902552<br/> <a href="#">AbstractPlus</a>   Full Text: <a href="#">PDF</a>(224 KB) IEEE CNF</p>   |
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